

Abstract of the Disclosure

An electrical connection and a method of electrically coupling are disclosed. In one embodiment, a circuit substrate with a first set of circuitry has a bonding pad mounted to a surface of the circuit board. The bonding pad is electrically coupled to the first set of circuitry. A flexible circuit substrate with a second set of circuitry has a connecting pad mounted to a surface of the flexible circuit substrate facing the surface of the circuit board. The connecting pad is electrically coupled to the second set of circuitry. A ball of conductive material is mounted on the bonding pad. A clamping device presses the connecting pad to the ball of conductive material.